





PART NO. SUFFIX	SOLDER BALL ALLOY		
-61	Sn63Pb37		
-61F*	Sn96.5Ag3.0Cu0.5		
*RoHS Compliant			

- 1) Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material; Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- $0.25\mu m$ [10μ "] Au over $1.27\mu m$ [50μ "] Ni (min.).
- 3) Solder Balls: See Table.

Description: Giga-SnaP BGA foot, 17x17 array, 0.8mm pitch 15mm sq.

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ± 0.0254 mm [± 0.001 "], Pitches (from true position) ± 0.0254 mm [± 0.001 "], substrate thickness tolerance ± 10 %, all other tolerances ± 0.127 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA256K-B-61 Specification			
SF-BGA256K-B-61F Specification			
•	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com		

- N/A FINISH: N/A	STATUS: Released	SHEET 1 OF 1	REV. A
	ENG: S. Faiz	Drawn By: D. Hauer	
	File: SF-BGA256K-B-61	DATE: 12/09/13	SCALE: 4:1